

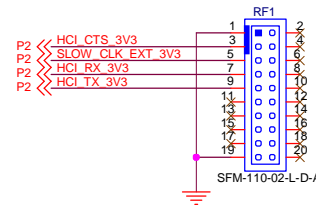
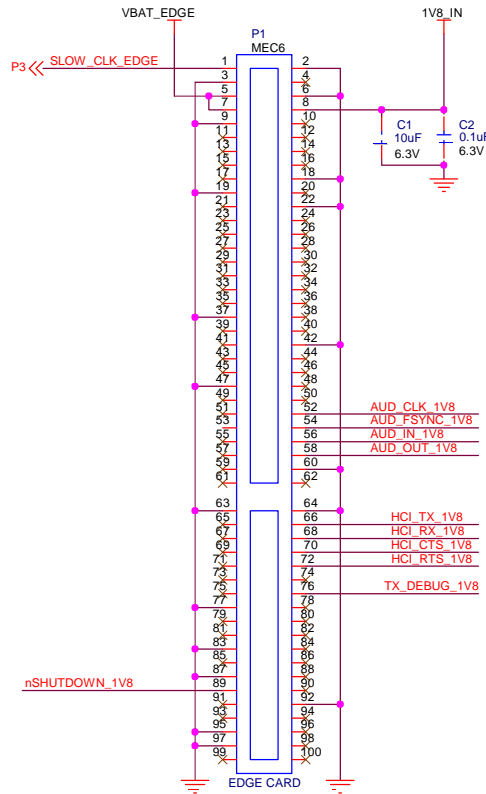
*Miguel Sanchez, Dana Myers  
Lit # TIDR111  
Reference Design #CC256XEM-RD*

## ***TI Designs: CC256x Bluetooth® Reference Design***

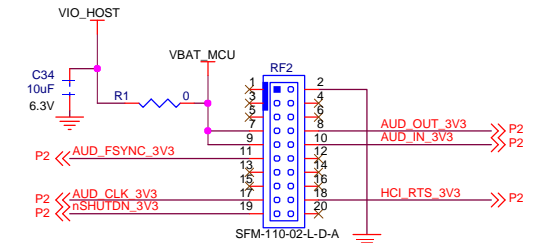


REVISION HISTORY

Added C32, C36  
 R33 0 ohm resistor was deleted  
 R33 when installed connected MLD0\_OUT to VBAT\_CC  
 Delete net SLOW\_CLK\_DBG, connect net SLOW-CLK-EDGE to P2 pin 10.

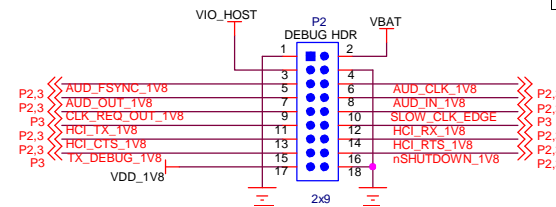


RF1 Connector		RF2 Connector	
Pin#	EM Adapter Pin Assignment	Pin#	EM Adapter Pin Assignment
1	GND	1	+1.8V (Optional)
3	MODULE_UART_CTS	3	+1.8V (Optional)
5	SLOW_CLK	5	+1.8V (Optional)
7	MODULE_UART_RX	7	+3.3V
9	MODULE_UART_TX	9	+3.3V
11	IPC_SDA	11	MODULE_AUDIO_FSYNCR
13	IPC_SCL	13	RF_GPIO2
15	SDIO_CLK	15	CC_RSTN
17	SDIO_CMD	17	MODULE_AUDIO_CLK
19	GND	19	WCS_NSHUTDR
2	SDIO_D0	2	GND
4	SDIO_D1	4	ANALOG_AUDIO_DATA_LEFT
6	SDIO_D2	6	ANALOG_AUDIO_DATA_RIGHT
8	SDIO_D3	8	MODULE_AUDIO_DATA_OUT
10	RF_GPIO0	10	MODULE_AUDIO_DATA_IN
12	RF_GPIO1	12	USBM
14	SPL_CS0	14	USBP
16	SPL_CLK	16	NC
18	SPL_MOSI	18	MODULE_UART_RTS
20	SPL_MISO	20	RF_GPIO3



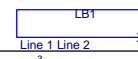
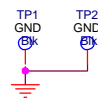
Configuration Notes:

	01-EM	02-COM
RF1	Install	Removed
RF2	Install	Removed

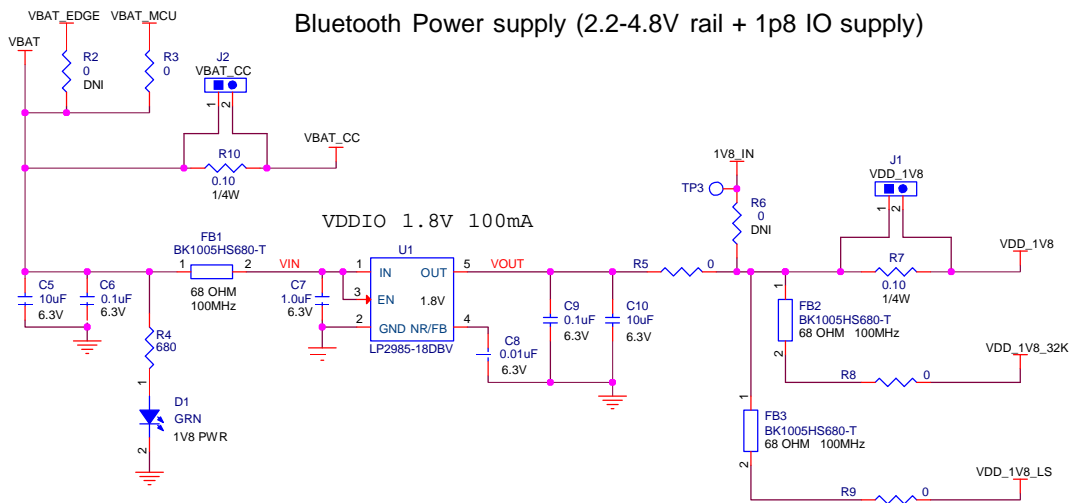


Board Interface

		Title	
		CC256xQFN-EM	
Designer	Approval	Size	Rev
CRAIG BOHREN	JOHN MCGDOWELL	B	1.2B
Drawn By	Layout	EDGE No	Date
JOHN MCGDOWELL	JOHN MCGDOWELL	6546200	Wednesday, July 10, 2013
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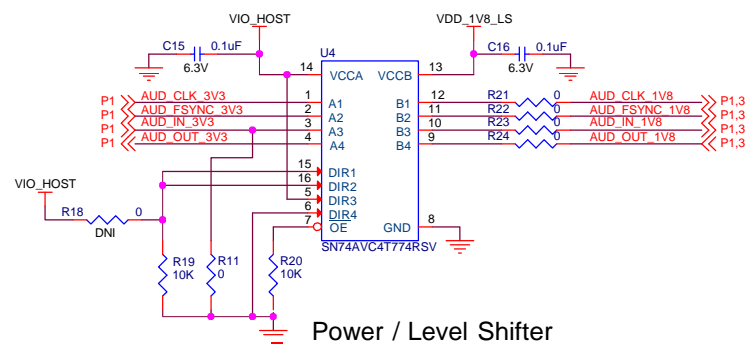
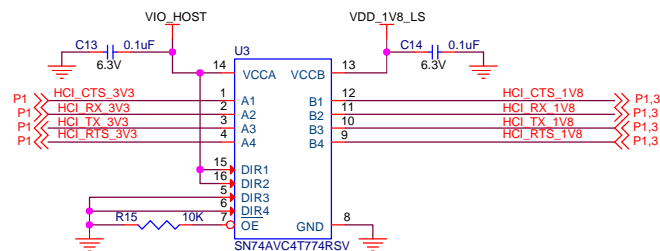
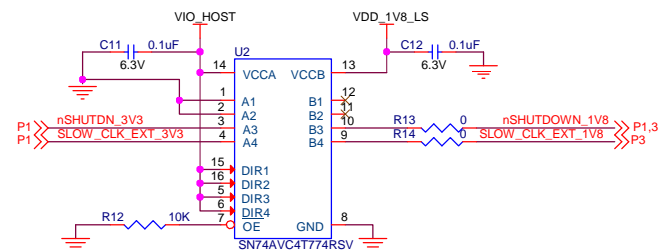
### Bluetooth Power supply (2.2-4.8V rail + 1p8 IO supply)



#### Configuration Notes:

	01-EM	02-COM
R2	Removed	Install
R3	Install	Removed

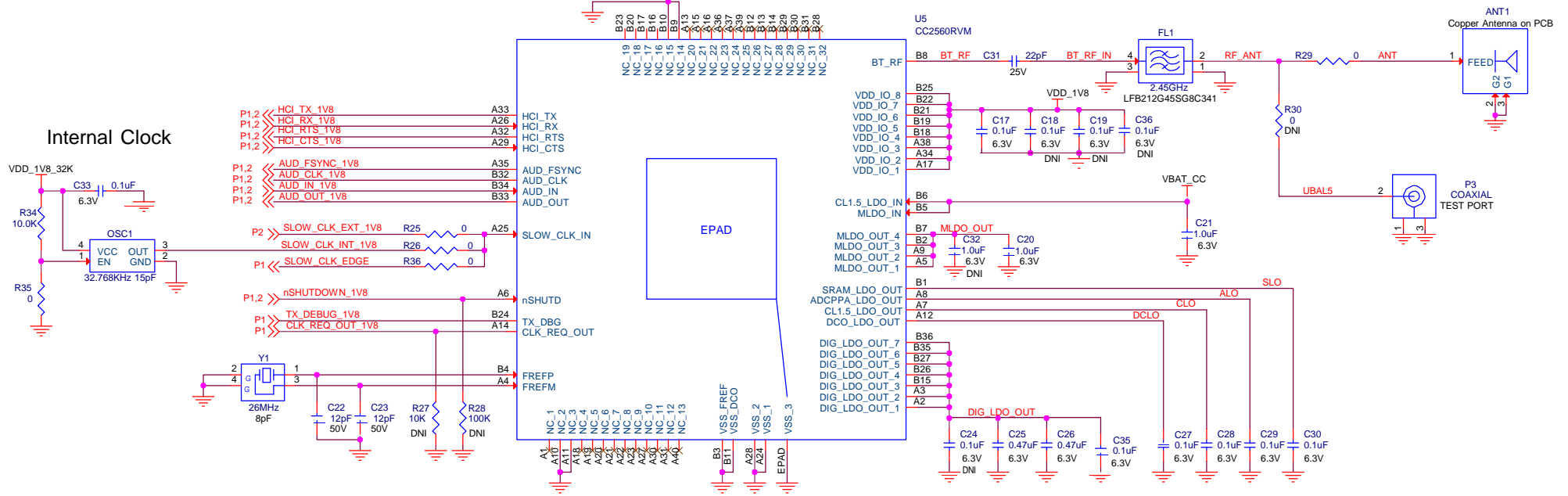
### Level Shifters



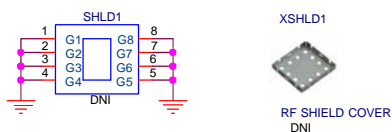
### Power / Level Shifter

Title <b>CC256xQFN-EM</b>		
Size B	EDGE No 6546200	Rev 1.2B
Date	Wednesday, July 10, 2013	Page 2 of 3

CC256x HCI Class 1.5 capable Bluetooth device



CC256xQFN



Title CC256xQFN-EM		
Size B	EDGE No 6546200	Rev 1.2B
Date	Wednesday, July 10, 2013	Page 3 of 3

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